## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE DECLARATION FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am an original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled:

## METHOD FOR MAKING A BLADE MATERIAL AND BLADE MATERIAL MANUFACTURED THEREBY

the specification of which	h:		
_X is attached hereto	; or		
was filed on	, 20	003 as U.S. Application	Serial No.
I hereby state that I have specification, including therein.	e reviewed and under the claims, as amende	rstand the contents of t ed by an amendment, if	he above identified any, specifically referred to
I acknowledge the duty in accordance with Title	to disclose all inform 37, Code of Federal	nation known to me that Regulations, § 1.56.	at is material to patentability
	FOREIGN	PRIORITY CLAIM	
foreign application(s) fo	r patent or inventor' cation for patent or in	s certificate listed below enventor's certificate ha	s Code § 119(a)-(d) of any w and have also identified ving a filing date before that
No such foreign app	olications have been t	filed	
X such foreign applica	tion have been filed	as follows:	
EARLIEST FOREIGN (6 MONTHS FOR DES			
Application Number	Country	Date of Filing	Priority Claimed Under 35 USC 119
10-2003-0100001	Korea	December 30, 2003	X Yes No
			Yes No

CLAIM FOR BENEFIT OF EARLIER U.S. PROVISIONAL APPLICATE to the state of the state o	ΓIONS
eby claim priority benefits under Title 35, United States Code §119(e), of any isional patent application(s) listed below:	ΓIONS
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no such U.S. provisional applications have been filed.	
Tough II S. provisional amplication have the Clades C. II	
such U.S. provisional application have been filed as follows:	
Application Number Date of Filing Priority Claimed Under 35 USC 119	
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Yes No	
Yes No	
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Yes No	
CLAIM FOR BENEFIT OF EARLIER U.S./PCT APPLICATION(S	<u> </u>
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eby claim the benefit under Title 35, United States Code, §120 of the United States (Soliton) is ted below and insofar as the subject matter of each of the alries of	States
cation(s) listed below and, insofar as the subject matter of each of the claims of cation is not disclosed in the prior United States application in the manner pro	)I INIS wided by 1
paragraph of Title 35, United States Code, §112, I acknowledge the duty to d	isclose all
	ederal
mation that is material to patentability in accordance with Title 37, Code of Fe	or applica
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mation that is material to patentability in accordance with Title 37, Code of Fe alations, §1.56 which became available to me between the filing date of the printernational or PCT international filing date of this application:  no such U.S./PCT applications have been filed.	••
mation that is material to patentability in accordance with Title 37, Code of Fe alations, §1.56 which became available to me between the filing date of the printernational or PCT international filing date of this application:  no such U.S./PCT applications have been filed.	••
mation that is material to patentability in accordance with Title 37, Code of Fe clations, §1.56 which became available to me between the filing date of the prithe national or PCT international filing date of this application:  no such U.S./PCT applications have been filed.  such U.S./PCT application have been filed as follows:	of Filing

Docket No.

Docket No.	

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

I hereby appoint:

All practitioners at Customer Number 24998

all of **Dickstein Shapiro Morin & Oshinsky LLP**, 2101 L Street NW, Washington, DC 20037-1526, jointly, and each of them severally, my attorneys at law/patent agent(s), with full power of substitution, delegation and revocation, to prosecute this application, to make alterations and amendments therein, to receive the patent, and to transact all business in the U. S. Patent and Trademark Office connected therewith.

Please mail all correspondence to Stephen A. Soffen, whose address is:

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Please direct telephone calls to: Stephen A. Soffen at (202) 828-4879.

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Docket No.

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